

MOS FIELD EFFECT TRANSISTOR 2SK3641

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3641 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

ORDERING INFORMATION

| PART NUMBER | PACKAGE |
|-------------|-----------------|
| 2SK3641-ZK | TO-252 (MP-3ZK) |

FEATURES

· Low on-state resistance

 $R_{DS(on)1}$ = 14 m Ω MAX. (VGS = 10 V, ID = 18 A) $R_{DS(on)2}$ = 25 m Ω MAX. (VGS = 4.5 V, ID = 15 A)

- Low Ciss: Ciss = 930 pF TYP.
- Built-in gate protection diode

(TO-252)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

| Drain to Source Voltage (Vgs = 0 V) | VDSS | 30 | V |
|-------------------------------------|-----------------------|-------------|----|
| Gate to Source Voltage (VDS = 0 V) | Vgss | ±20 | V |
| Drain Current (DC) (Tc = 25°C) | ID(DC) | ±36 | Α |
| Drain Current (pulse) Note1 | I _{D(pulse)} | ±140 | Α |
| Total Power Dissipation (Tc = 25°C) | P _{T1} | 29 | W |
| Total Power Dissipation | P _{T2} | 1.0 | W |
| Channel Temperature | Tch | 150 | °C |
| Storage Temperature | T _{stg} | -55 to +150 | °C |
| Single Avalanche Current Note2 | las | 19 | Α |
| Single Avalanche Energy Note2 | Eas | 36 | mJ |

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting T_{ch} = 25°C, V_{DD} = 15 V, R_G = 25 Ω , L = 100 μ H, V_{GS} = 20 \rightarrow 0 V

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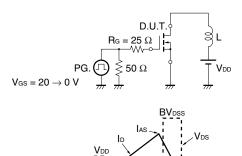


ELECTRICAL CHARACTERISTICS (TA = 25°C)

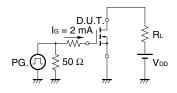
| CHARACTERISTICS | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|------------------------------------------|----------------------|------------------------------------------------|------|------|------|-----------|
| Zero Gate Voltage Drain Current | IDSS | V _{DS} = 30 V, V _{GS} = 0 V | | | 10 | μA |
| Gate Leakage Current | Igss | V _{GS} = ±20 V, V _{DS} = 0 V | | | ±10 | μΑ |
| Gate Cut-off Voltage | V _{GS(off)} | V _{DS} = 10 V, I _D = 1 mA | 1.5 | | 2.5 | V |
| Forward Transfer Admittance Note | y fs | V _{DS} = 10 V, I _D = 18 A | 5.5 | 11 | | S |
| Drain to Source On-state Resistance Note | R _{DS(on)1} | V _{GS} = 10 V, I _D = 18 A | | 11 | 14 | $m\Omega$ |
| | R _{DS(on)2} | V _{GS} = 4.5 V, I _D = 15 A | | 17 | 25 | mΩ |
| Input Capacitance | Ciss | V _{DS} = 10 V | | 930 | | pF |
| Output Capacitance | Coss | V _{GS} = 0 V | | 250 | | pF |
| Reverse Transfer Capacitance | Crss | f = 1 MHz | | 160 | | pF |
| Turn-on Delay Time | t _{d(on)} | V _{DD} = 15 V, I _D = 18 A | | 9.4 | | ns |
| Rise Time | tr | V _{GS} = 10 V | | 8.6 | | ns |
| Turn-off Delay Time | td(off) | R _G = 10 Ω | | 34 | | ns |
| Fall Time | tf | | | 11 | | ns |
| Total Gate Charge | QG | V _{DD} = 24 V | | 22 | | nC |
| Gate to Source Charge | Qgs | V _{GS} = 10 V | | 3.6 | | nC |
| Gate to Drain Charge | Q _{GD} | I _D = 36 A | | 7.4 | | nC |
| Body Diode Forward Voltage Note | V _{F(S-D)} | I _F = 36 A, V _{GS} = 0 V | | 1.0 | | V |
| Reverse Recovery Time | trr | IF = 36 A, VGS = 0 V | | 24 | | ns |
| Reverse Recovery Charge | Qrr | di/dt = 100 A/μs | | 15 | | nC |

Note Pulsed: PW \leq 350 μ s, Duty Cycle \leq 2%

TEST CIRCUIT 1 AVALANCHE CAPABILITY

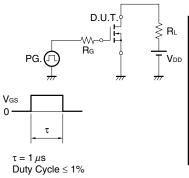


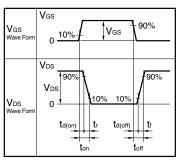




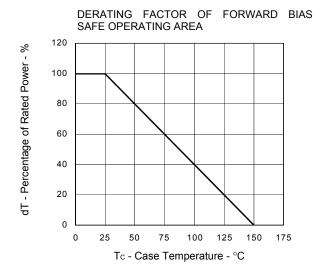
Starting Tch

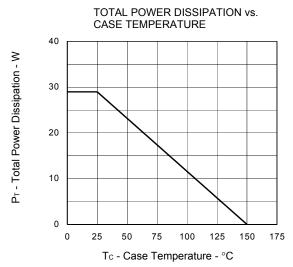
TEST CIRCUIT 2 SWITCHING TIME



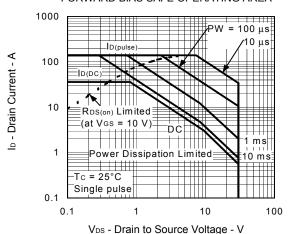


TYPICAL CHARACTERISTICS (TA = 25°C)

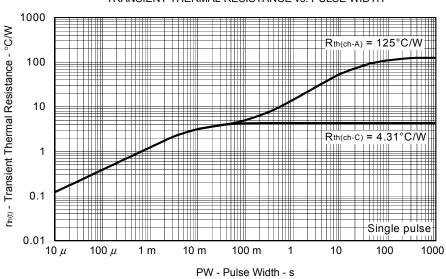




FORWARD BIAS SAFE OPERATING AREA



TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

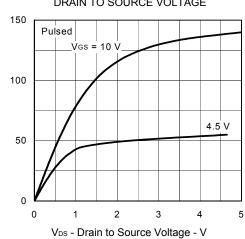


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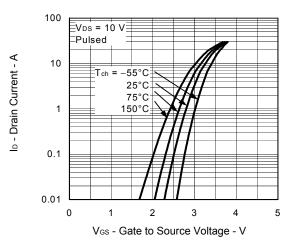
lo - Drain Current - A

VGS(off) - Gate Cut-off Voltage - V

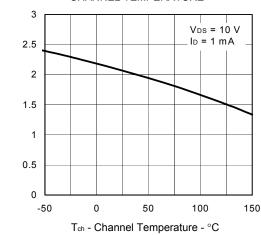
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



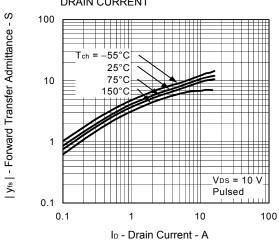
FORWARD TRANSFER CHARACTERISTICS



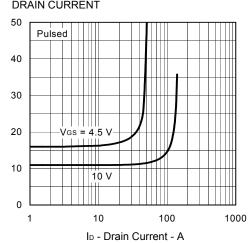
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



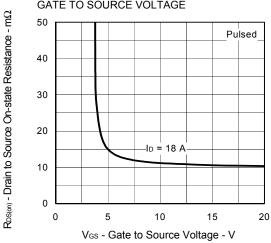
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

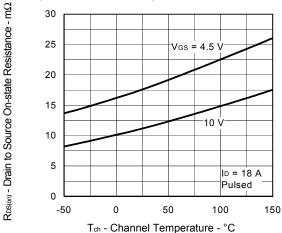


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

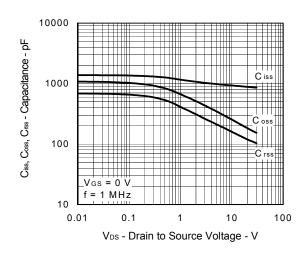


R_{DS(m)} - Drain to Source On-state Resistance - mΩ

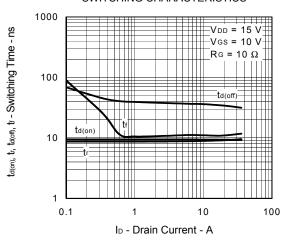
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



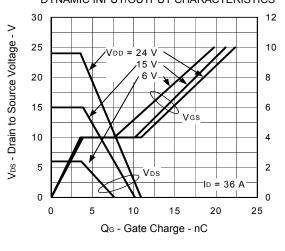
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



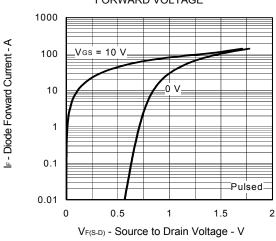
SWITCHING CHARACTERISTICS



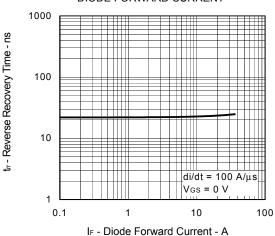
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



INDUCTIVE LOAD 100 V-ILAS = 19 A IAS = 19 A IAS = 19 A VDD = 15 V RG = 25 Ω Vcs = 20 \rightarrow 0 V Starting Toh = 25 $^{\circ}$ C

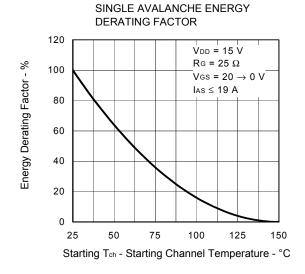
0.1

L - Inductive Load - mH

10

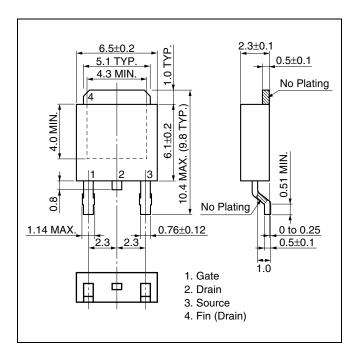
0.01

SINGLE AVALANCHE CURRENT vs.

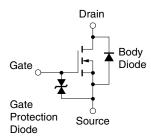


★ PACKAGE DRAWING (Unit: mm)

TO-252 (MP-3ZK)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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